



 MICROCHIP			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e3				
Semiconductor Device Type: RWX 008 WDFN 2x2x0.8mm MatteTin													
Basic Substance			CAS Number	Sub-Component	% Total Weight	mg/part	ppm	5.12	(mg) Total	Mold Compound	% of Total Weight	47.41	
Silica, fused			60676-86-0	Mold Compound	42.669	4.608	426.690		Silica, fused	60676-86-0	90.00		
Epoxy Resin			Trade Secret	Mold Compound	2.299	0.248	22.994		Epoxy Resin	Trade Secret	4.85		
Phenolic Resin			Trade Secret	Mold Compound	2.299	0.248	22.994		Phenolic Resin	Trade Secret	4.85		
Carbon Black			1333-86-4	Mold Compound	0.142	0.015	1.422		Carbon Black	1333-86-4	0.30		
Copper			7440-50-8	Lead Frame	44.713	4.829	447.135		Total				100.00
Tin			7440-31-5	Lead Frame	0.115	0.012	1.148	4.96	(mg) Total	Lead Frame	% of Total Weight	45.9	
Silver			7440-22-4	Lead Frame	0.874	0.094	8.744		Copper	7440-50-8	97.42		
Zinc			7440-66-6	Lead Frame	0.083	0.009	826		Tin	7440-31-5	0.25		
Chromium			7440-47-3	Lead Frame	0.115	0.012	1.148		Silver	7440-22-4	1.91		
Silver			7440-22-4	Die Attach	0.990	0.107	9.900		Zinc	7440-66-6	0.18		
1,1'-(Methylenedi-p-phenylene)bismaleimide			13676-54-5	Die Attach	0.110	0.012	1.100		Chromium	7440-47-3	0.25		
Silicon			7440-21-3	Chip (Die)	4.700	0.508	47.000		Total				100.00
Gold			7440-57-5	Wire Bond	0.170	0.018	1.700	0.12	(mg) Total	Die Attach	% of Total Weight	1.1	
Tin			7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	0.720	0.078	7.200		Silver	7440-22-4	90.00		
				TOTALS:	100.000	10.800	1,000,000		1,1'-(Methylenedi-p-phenylene)bismaleimide	13676-54-5	10.00		
									Total				100.00
0.0108 g Total Mass													
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)													
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and for analytical test data.													
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.													
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offering/industries/chemicals/plastics/													
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.													
Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.													
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table													
10.80													
100.00													

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Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

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